

ABSTRACT

The purpose of this study is to characterize the single-event effects (SEE) performance due to heavy-ion irradiation of the TPS7H4011-SP. Heavy-ions with LET_{EFF} of $75 \text{ MeV} \times \text{cm}^2 / \text{mg}$ were used to irradiate four production devices. Flux of approximately $10^5 \text{ ions/cm}^2 \times \text{s}$ and fluence of 10^7 ions / cm^2 per run were used for the characterization. The results demonstrated that the TPS7H4011-SP is SEL-free up to $75 \text{ MeV} \cdot \text{cm}^2 / \text{mg}$ at $T = 125^\circ\text{C}$ and SEB/SEGR free up to $75 \text{ MeV} \times \text{cm}^2 / \text{mg}$ at $T = 25^\circ\text{C}$. Output signals including V_{OUT} (3% window), SS_TR (edge trigger at 20% below nominal) and PWRGD (edge trigger at 500mV below nominal) were monitored to check for transients and SEFIs. The results showed the device is SET and SEFI free up to $75 \text{ MeV} \times \text{cm}^2 / \text{mg}$ at $T = 25^\circ\text{C}$.

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1 Introduction

The TPS7H4011-SP is a 14V, 12A synchronous buck converter optimized for use in a space environment. The peak current mode converter obtains high efficiency with good transient performance and reduced component count.

The wide voltage range of the TPS7H4011-SP enables the device to be used as a point of load regulator to convert directly from a 12V or 5V rail. The output voltage start-up ramp is controlled by the SS_TR pin. Power sequencing is possible with the EN and PWRGD pins.

The device can be configured with up-to four devices in parallel without an external clock for increased current capabilities. Additionally, various features are included such as differential remote sensing, selectable current limit, a flexible fault input pin, and configurable compensation.

The device is offered in a 30-pin ceramic package. General device information and test conditions are listed in [Table 1-1](#). For more detailed technical specifications, user guides, and application notes, see [TPS7H4011-SP product page](#).

Table 1-1. Overview Information

Description ⁽¹⁾	Device Information
TI Part Number	TPS7H4011-SP
Orderable Number	5962R2122101VXC
Device Function	Synchronous Buck Converter
Technology	LBC7 (Linear BiCMOS 7)
Exposure Facility	Radiation Effects Facility, Cyclotron Institute, Texas A&M University (15 MeV/nucleon)
Heavy Ion Fluence per Run	1.00×10^7 ions / cm ²
Irradiation Temperature	25°C (for SEB/SEGR testing), 25°C (for SET testing), and 125°C (for SEL testing)

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2 Single-Event Effects (SEE)

The primary concern for the TPS7H4011-SP is the robustness against the destructive single-event effects (DSEE): single-event latch-up (SEL), single-event burnout (SEB), and single-event gate rupture (SEGR). In mixed technologies such as the BiCMOS process used on the TPS7H4011-SP, the CMOS circuitry introduces a potential for SEL susceptibility.

SEL can occur if excess current injection caused by the passage of an energetic ion is high enough to trigger the formation of a parasitic cross-coupled PNP and NPN bipolar structure (formed between the p-sub and n-well and n+ and p+ contacts) (1,2). The parasitic bipolar structure initiated by a single-event creates a high-conductance path (inducing a steady-state current that is typically orders-of-magnitude higher than the normal operating current) between power and ground that persists (is *latched*) until power is removed, the device is reset, or until the device is destroyed by the high-current state. The TPS7H4011-SP was tested for SEL at the maximum recommended input voltage (V_{IN}) of 14V. The output load was configured to provide a constant resistance value of 0.2718Ω to create a 12A load on the output. During testing of the four devices, the TPS7H4011-SP did not exhibit any SEL with heavy-ions with $LET_{EFF} = 75\text{MeV} \times \text{cm}^2 / \text{mg}$ at flux of approximately 5×10^4 ions / $\text{cm}^2 \times \text{s}$, fluence of approximately 10^7 ions / cm^2 , and a die temperature of $\sim 125^\circ\text{C}$.

The TPS7H4011-SP was evaluated for SEB/SEGR at a maximum voltage of 14V in enabled and disabled mode. Because it has been shown that the MOSFET susceptibility to burnout decrement with temperature (5), the device was evaluated while operating under room temperatures. The device was tested with no external thermal control device. During the SEB/SEGR testing, not a single current event was observed, demonstrating that the TPS7H4011-SP is SEB/SEGR-free up to $LET_{EFF} = 75\text{MeV} \times \text{cm}^2 / \text{mg}$ at a flux of approximately 5×10^4 ions / $\text{cm}^2 \times \text{s}$, fluences of approximately 10^7 ions / cm^2 , and a die temperature of approximately 25°C .

The TPS7H4011-SP was characterized at V_{IN} of 5V and 12V. During SET testing the V_{OUT} , SS_TR, and PWRGD signals were monitored. During the SET testing, not a single transient was observed, demonstrating that the TPS7H4011-SP is SET/SEFI-free up to $LET_{EFF} = 75\text{MeV} \times \text{cm}^2 / \text{mg}$ at a flux of approximately 5×10^4 ions / $\text{cm}^2 \times \text{s}$, fluences of approximately 10^7 ions / cm^2 , and a die temperature of approximately 25°C . For more details on the SET testing of the TPS7H4011-SP, see [Single-Event Transients \(SET\)](#).

3 Device and Test Board Information

The TPS7H4011-SP is packaged in a 30-pin thermally-enhanced ceramic package as shown in [Figure 3-1](#). The TPS7H4011-SP evaluation module (EVM) was used to evaluate the performance and characteristics of the TPS7H4011-SP under heavy ion radiation. The TPS7H4011EVM-CVAL EVM is shown in [Figure 3-2](#). The EVM schematic is shown in [Figure 3-3](#).

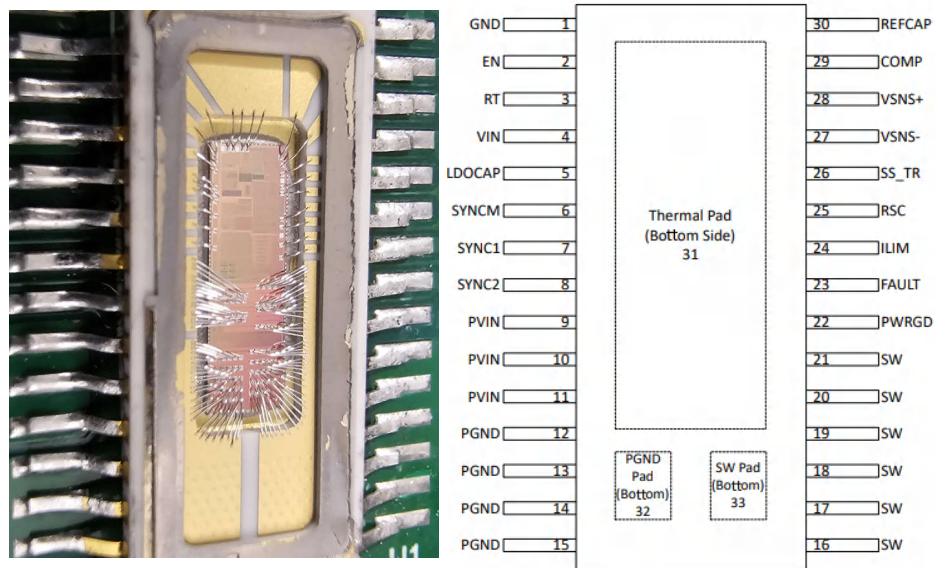


Figure 3-1. Photograph of Delidded TPS7H4011-SP (Left) and Pinout Diagram (Right)

The package was delidded to reveal the die face for all heavy-ion testing.

Jumper on J5 was populated, J6 was configured in the 2-3 position, J7 was configured in the 1-2 position, and J10 was configured in the 1-2 position for all testing

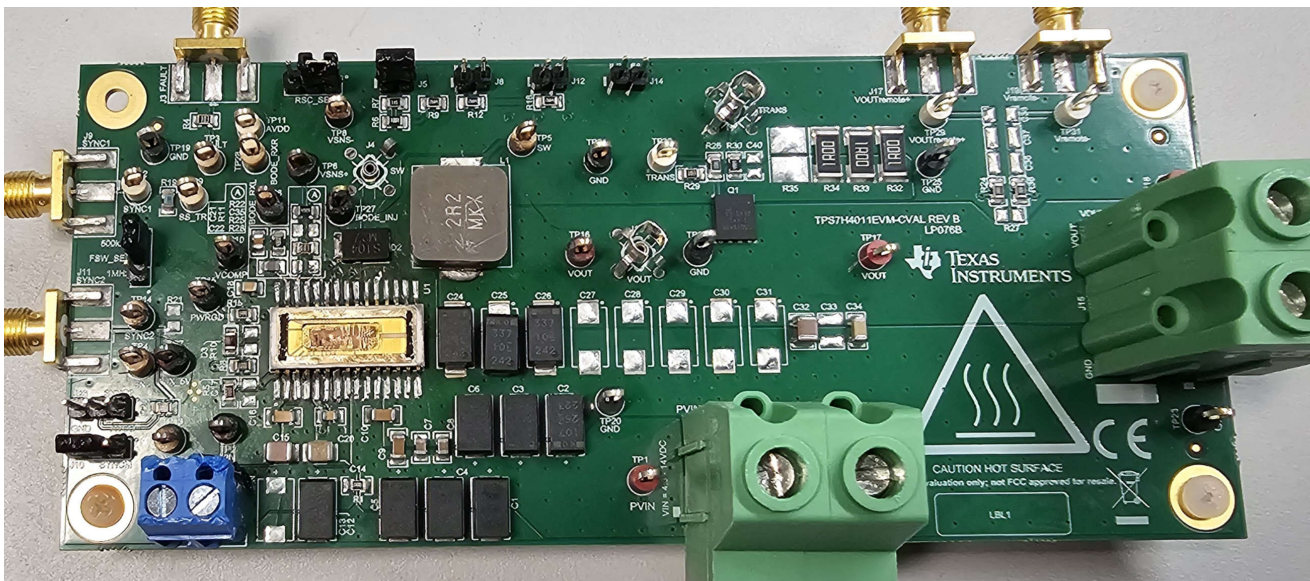


Figure 3-2. TPS7H4011-SP EVM Top View

PVIN = VIN = 4.5-14 VDC

TPS7H4011-SP Converter

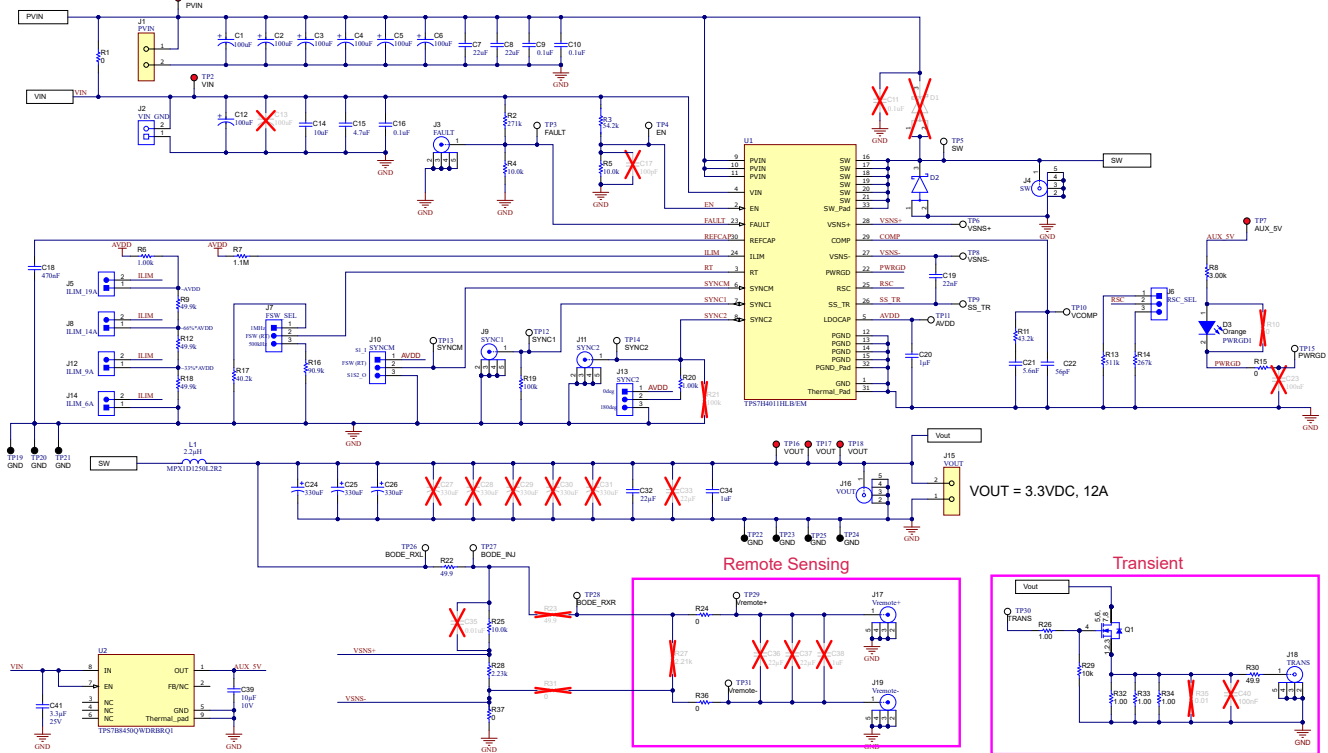


Figure 3-3. TPS7H4011-SP EVM Schematics

4 Irradiation Facility and Setup

The heavy-ion species used for the SEE studies on this product were provided and delivered by the TAMU Cyclotron Radiation Effects Facility using a superconducting cyclotron and an advanced electron cyclotron resonance (ECR) ion source. At the fluxes used, ion beams had good flux stability and high irradiation uniformity over a 1in diameter circular cross-sectional area for the in-air station. Uniformity is achieved by magnetic defocusing. The flux of the beam is regulated over a broad range spanning several orders of magnitude. For these studies, ion flux of 1.02×10^4 to 1.12×10^5 ions/cm²·s were used to provide heavy-ion fluences of 1.00×10^6 to 1.00×10^7 ions/cm².

For the experiments conducted on this report, there was one ion used ¹⁶⁵Ho. ¹⁶⁵Ho was used to obtain LET_{EFF} of 75MeV × cm²/ mg. The total kinetic energies for the ion was:

- ¹⁶⁵Ho = 2.474GeV (15MeV/nucleon)
 - Ion uniformity for these experiments was between 95% and 96%

Figure 4-1 shows the TPS7H4011EVM-CVAL used for data collection at the TAMU facility. Although not visible in this photo, the beam port has a 1mil Aramica window to allow in-air testing while maintaining the vacuum within the accelerator with only minor ion energy loss. The in-air gap between the device and the ion beam port window was maintained at 40mm for all runs.

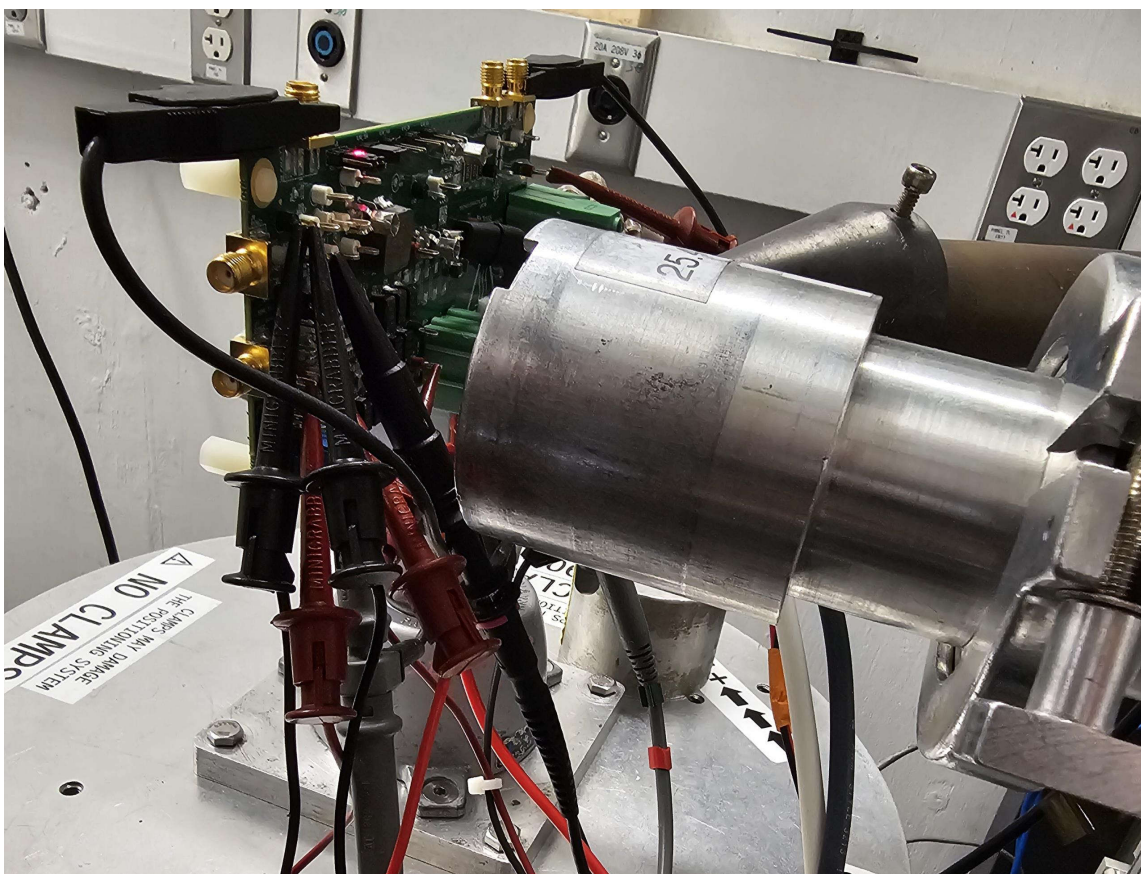


Figure 4-1. Photograph of the TPS7H4011-SP EVM in Front of the Heavy-Ion Beam Exit Port at the Texas A&M Cyclotron

5 Depth, Range, and LET_{EFF} Calculation

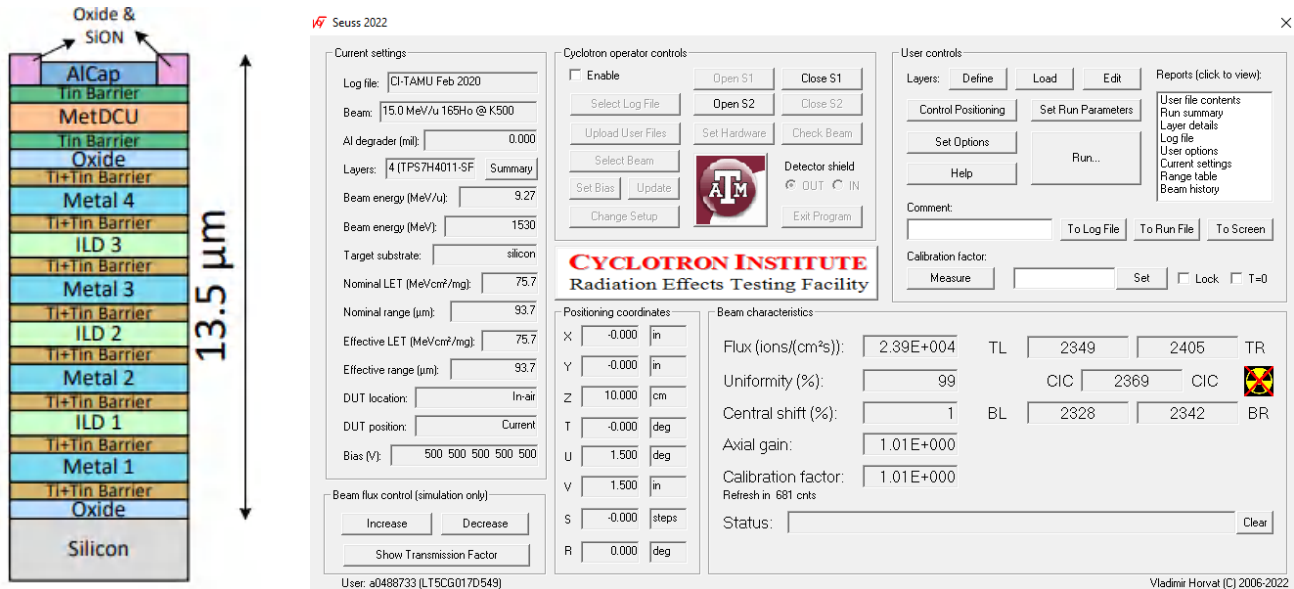


Figure 5-1. Generalized Cross-Section of the LBC7 Technology BEOL Stack on the TPS7H4011-SP (Left) and SEUSS 2020 Application Used to Determine Key Ion Parameters (Right)

The TPS7H4011-SP is fabricated in the TI Linear BiCMOS 250-nm process with a back-end-of-line (BEOL) stack consisting of four levels of standard thickness aluminum and Damascene copper. The total stack height from the surface of the passivation to the silicon surface is 13.5μm based on nominal layer thickness as shown in Figure 5-1. Accounting for energy loss through the 1-mil thick Aramica beam port window, the 40mm air gap, and the BEOL stack over the TPS7H4011-SP, the effective LET (LET_{EFF}) at the surface of the silicon substrate and the depth was determined with the SEUSS 2020 Software (provided by the Texas A&M Cyclotron Institute and based on the latest SRIM-2013 [7] models). The results are shown in Ion LET_{EFF}, Depth, and Range in Silicon.

Table 5-1. Ion LET_{EFF}, Depth, and Range in Silicon

Ion Type	Beam Energy (MeV/nucleon)	Angle of Incidence	Degrader Steps (#)	Degrader Angle	Range in Silicon (μm)	LET _{EFF} (MeV·cm ² / mg)
¹⁶⁵ Ho	15	0	0	0	97.2	75

6 Test Setup and Procedures

There were two input supplies used to power the TPS7H4011-SP which provided V_{IN} and EN. The V_{IN} for the device was provided through Channel 3 of an N6705C power module and ranged from 5 and 12V for SET to 14V for SEL and SEB/SEGR. EN was powered by Channel 1 of an E36311A power supply and ranged from 0V for SEB Off to 5V for all other testing.

The instrument used to load the TPS7H4011-SP was a Chroma E36300 E-Load that was used in Constant Resistance (CR) mode. The value of CR was 0.2718Ω and provided a 12A load on the device.

The primary signal monitored on the EVM was V_{OUT} and this was done using a Tektronix MSO58B with a 3% window trigger based on the nominal measured value of V_{OUT} . All SEB On, SEL, and SET testing used these conditions with only the SEB Off testing having different conditions. The conditions for SEB Off were a positive edge trigger at 0.5V which would check to see if the device ever incorrectly turned on while it was disabled. The secondary signals monitored were the PWRGD and SS_TR pins. These signals were monitored on PXIe-5172 cards and were configured to have edge triggers. The PG signal had an edge trigger at 500mV below nominal and the SS signal had an edge trigger at 20% below nominal.

All equipment other than the MSO58B was controlled and monitored using a custom-developed LabVIEW™ program (PXI-RadTest) running on a HP-Z4™ desktop computer. The computer communicates with the PXI chassis via an MXI controller and NI PXIe-8381 remote control module. The MSO58B was used using the manufacturer interface. The MSO was set to fast-frame for all SET data collection.

[Equipment Settings and Parameters Used During the SEE Testing of the TPS7H4011-SP](#) shows the connections, limits, and compliance values used during the testing. [Figure 6-1](#) shows a block diagram of the setup used for SEE testing of the TPS7H4011-SP.

Table 6-1. Equipment Settings and Parameters Used During the SEE Testing of the TPS7H4011-SP

Pin Name	Equipment Used	Capability	Compliance	Range of Values Used
V_{IN}	N6705C (CH # 3)	60V, 17A	5A	5 to 14V
EN	E36311A (CH # 1)	6V, 5A	0.1A	0V, 5V
V_{OUT}	MSO58B	1GS/s	—	250 GS/s
SS_TR	PXIe-5172 (1)	100MS/s	—	100MS/s
PWRGD	PXIe-5172 (2)	100MS/s	—	100MS/s
V_{OUT}	Chroma E36300 Load	80A	High	—

All boards used for SEE testing were fully checked for functionality. Dry runs were also performed to ensure that the test system was stable under all bias and load conditions prior to being taken to the TAMU facility. During the heavy-ion testing, the LabVIEW control program powered up the TPS7H4011-SP device and set the external sourcing and monitoring functions of the external equipment. After functionality and stability was confirmed, the beam shutter was opened to expose the device to the heavy-ion beam. The shutter remained open until the target fluence was achieved (determined by external detectors and counters). During irradiation, the NI scope cards continuously monitored the signals. When the output exceeded the pre-defined 3% window trigger, a data capture was initiated. No sudden increases in current were observed (outside of normal fluctuations) on any of the test runs and indicated that no SEL or SEB/SEGR events occurred during any of the tests.

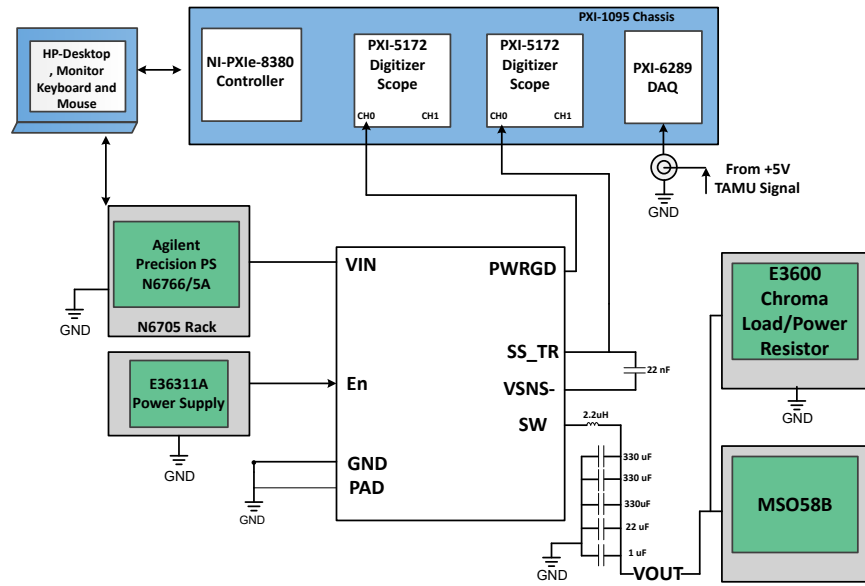


Figure 6-1. Block Diagram of the SEE Test Setup for the TPS7H4011-SP

7 Destructive Single-Event Effects (DSEE)

7.1 Single-Event Latch-up (SEL) Results

During the SEL testing the device was heated to 125°C by using a Closed-Loop PID controlled heat gun (MISTRAL 6 System (120V, 2400W)). The temperature of the die was verified using thermal camera prior to exposure to heavy ions.

The species used for the SEL testing was Holmium (¹⁶⁵Ho at 15MeV/nucleon). For the ¹⁶⁵Ho ion an incidence angle of 0° was used to achieve an LET_{EFF} = 75MeV·cm² / mg (For more details, see [Ion LET_{EFF}, Depth, and Range in Silicon](#)). The kinetic energy in the vacuum for this ions is 2.474GeV. Flux of approximately 5 × 10⁴ ions/cm² × s and a fluence of approximately 10⁷ ions/cm² per run was used. Run duration to achieve this fluence was approximately four minutes. The four devices were powered up and exposed to the heavy-ions using the maximum recommended input voltage of 14V with the maximum recommended load of 12A. No SEL events were observed during all four runs, indicating that the TPS7H4011-SP is SEL-free up to 75MeV × cm²/mg. [Table 7-1](#) shows the SEL test conditions and results. [Figure 7-1](#) shows a plot of the current versus time for run 1.

Table 7-1. Summary of TPS7H4011-SP SEL Test Condition and Results

Run Number	Unit Number	Ion	LET _{EFF} (MeV × cm ² /mg)	Flux (ions × cm ² /mg)	Fluence (Number ions)	V _{IN}	I _{OUT} (A)	SEL (# Events)
1	1	¹⁶⁵ Ho	75	3.09 × 10 ⁴	1 × 10 ⁷	14	12	0
2	2	¹⁶⁵ Ho	75	5.58 × 10 ⁴	1 × 10 ⁷	14	12	0
3	3	¹⁶⁵ Ho	75	5.95 × 10 ⁴	1 × 10 ⁷	14	12	0
4	4	¹⁶⁵ Ho	75	6.93 × 10 ⁴	1 × 10 ⁷	14	12	0

Using the MFTF method shown in [Single-Event Effects \(SEE\) Confidence Interval Calculations](#) and combining (or summing) the fluences of the four runs at 125°C (4 × 10⁷), the upper-bound cross-section (using a 95% confidence level) is calculated as: σ_{SEL} ≤ 9.22 × 10⁻⁸ cm²/ device for LET_{EFF} = 75MeV × cm²/ mg and T = 125°C.

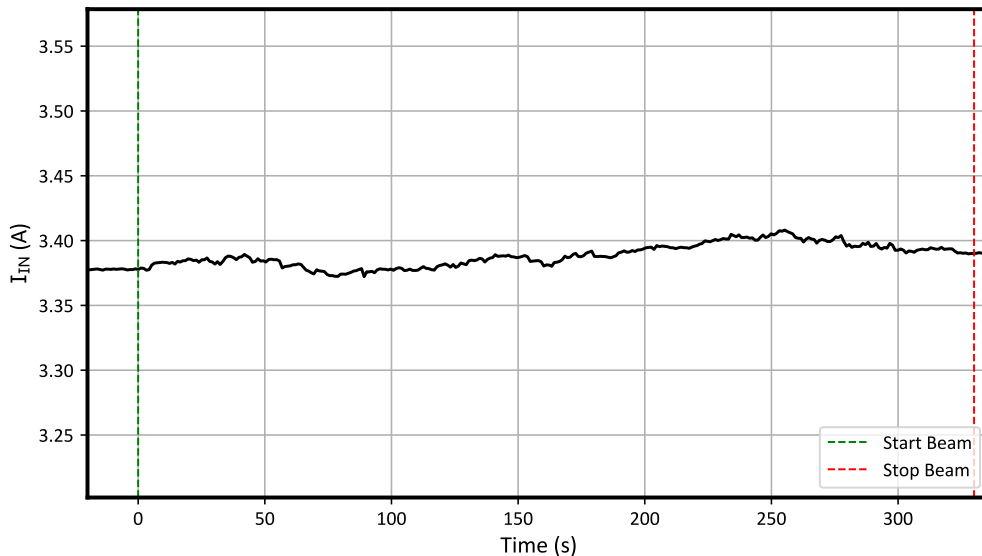


Figure 7-1. SEL Current versus Time for Run 1 of the TPS7H4011-SP at T = 125°C (V_{OUT} = 3.3V)

7.2 Single-Event Burnout (SEB) and Single-Event Gate Rupture (SEGR) Results

During the SEB/SEGR characterization, the device was tested at room temperature of approximately 25°C. The device was tested under both the enabled and disabled mode. For the SEB-OFF mode the device was disabled using the EN-pin by forcing 0V (using Channel 1 of a E36311A Keysight PS). During the SEB/SEGR testing with the device enabled/disabled, not a single input current event was observed.

The species used for the SEB testing was Homium (^{165}Ho @ 15MeV/nucleon). For the ^{165}Ho ion an angle of incidence of 0° was used to achieve an $\text{LET}_{\text{EFF}} = 75\text{MeV}\cdot\text{cm}^2/\text{mg}$ (for more details refer to [Ion LET_{EFF}, Depth, and Range in Silicon](#)). The kinetic energy in the vacuum for this ion is 2.474GeV (15-MeV/amu line). Flux of approximately 5×10^4 ions/cm²× s and a fluence of approximately 10^7 ions/cm² was used for the run. Run duration to achieve this fluence was approximately four minutes. The four devices (same as used in SEL testing) were powered up and exposed to the heavy-ions using the maximum recommended input voltage of 14-V with the max recommended load of 12A. No SEB/SEGR current events were observed during the eight runs, indicating that the TPS7H4011-SP is SEB/SEGR-free up to $\text{LET}_{\text{EFF}} = 75 \text{ MeV} \times \text{cm}^2/\text{mg}$ and across the full electrical specifications. [Summary of TPS7H4011-SP SEB/SEGR Test Condition and Results](#) shows the SEB/SEGR test conditions and results.

Table 7-2. Summary of TPS7H4011-SP SEB/SEGR Test Condition and Results

Run Number	Unit Number	ION	LET _{EFF} (MeV × cm ² /mg)	FLUX (ions × cm ² /mg)	FLUENCE (# ions)	Enabled Status	V _{IN}	I _{OUT} (A)	SEB EVENT?
5	1	¹⁶⁵ Ho	75	3.10×10^4	9.99×10^6	EN	14	12	No
6		¹⁶⁵ Ho	75	3.09×10^4	9.99×10^6	DIS	14	12	No
7	2	¹⁶⁵ Ho	75	5.92×10^4	1.00×10^7	EN	14	12	No
8		¹⁶⁵ Ho	75	5.56×10^4	1.00×10^7	DIS	14	12	No
9	3	¹⁶⁵ Ho	75	5.90×10^4	1.00×10^7	EN	14	12	No
10		¹⁶⁵ Ho	75	5.96×10^4	1.00×10^7	DIS	14	12	No
11	4	¹⁶⁵ Ho	75	6.72×10^4	1.00×10^7	EN	14	12	No
12		¹⁶⁵ Ho	75	6.91×10^4	1.00×10^7	DIS	14	12	No

Using the MFTF method described in [Single-Event Effects \(SEE\) Confidence Interval Calculations application report](#), the upper-bound cross-section (using a 95% confidence level) is calculated as:

$$\sigma_{\text{SEB}} \leq 4.61 \times 10^{-8} \text{ cm}^2/\text{device for } \text{LET}_{\text{EFF}} = 75\text{MeV} \times \text{cm}^2/\text{mg} \text{ and } T = 25^\circ\text{C}.$$

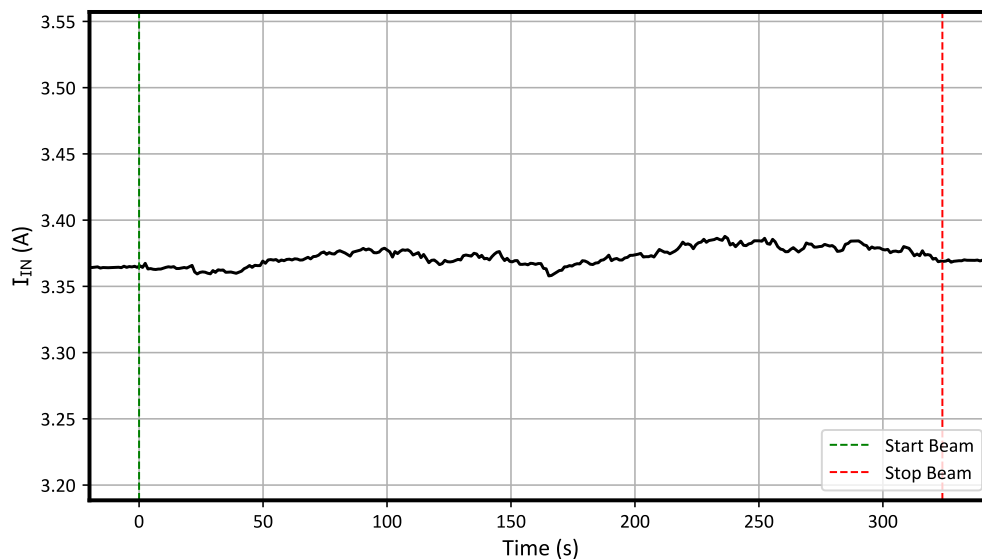


Figure 7-2. SEB On Current vs Time for Run 5 of the TPS7H4011-SP at T = 25°C (V_{OUT} = 3.3V)

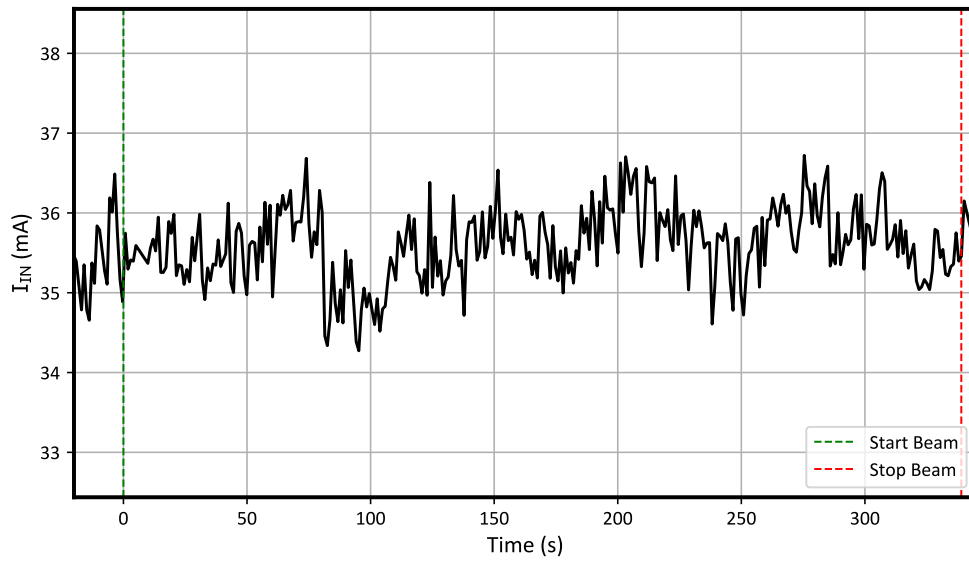


Figure 7-3. SEB Off Current vs Time for Run 6 of the TPS7H4011-SP at T = 25°C ($V_{OUT} = 0\text{-V}$)

8 Single-Event Transients (SET)

SETs are defined as heavy-ion-induced transients upsets on the VOUT, SS_TR, or PWRGD of the TPS7H4011-SP.

Testing was performed at room temperature (no external temperature control applied). The heavy-ion species used for the SET testing was Homium (^{165}Ho) for an $\text{LET}_{\text{EFF}} = 75\text{MeV} \times \text{cm}^2/\text{mg}$, for more details refer to [Ion LET_{EFF}, Depth, and Range in Silicon](#). Flux of approximately 5×10^4 ions/cm² × s and a fluence of 1×10^7 ions/cm², per run were used for the SET's characterization discussed on this chapter. Over the course of testing four devices, not a single transient or SEFI was recorded on any of the monitored signals indicating that the TPS7H4011-SP is SET/SEFI free up to $\text{LET}_{\text{EFF}} = 75\text{MeV} \times \text{cm}^2/\text{mg}$.

Waveform size, sample rate, trigger type, value, and signal for all scopes used is presented on [Table 8-1](#).

Table 8-1. Scope Settings

Scope Model	Trigger Signal	Trigger Type	Trigger Value	Record Length	Sample Rate
MSO58B	VOUT	Window	± 3 %	20µs/div	250MS/s
PXIe-5172 (1)	SS_TR	Edge/Negative	20%	20k	100MS/s
PXIe-5172 (2)	PWRGD	Edge/Negative	0.5-V Below nominal	20k	100MS/s

Table 8-2. Summary of TPS7H4011-SP SET Test Condition and Results

Run Number	Unit Number	ION	LET _{EFF} (MeV × cm ² /mg)	V _{IN} (V)	FLUX (ions × cm ² /mg)	Fluence (Number ions)	MSO58B V _{OUT} Number ≥ 3%	PXIe-5172 SS_TR Number	PXIe-5172 PWRGD Number
13	1	^{165}Ho	75	12	3.18×10^4	1.00×10^7	0	0	0
14	1	^{165}Ho	75	5	3.11×10^4	1.00×10^7	0	0	0
15	2	^{165}Ho	75	12	5.65×10^4	1.00×10^7	0	0	0
16	2	^{165}Ho	75	5	5.47×10^4	1.00×10^7	0	0	0
17	3	^{165}Ho	75	12	6.01×10^4	1.00×10^7	0	0	0
18	3	^{165}Ho	75	5	6.25×10^4	1.00×10^7	0	0	0
19	4	^{165}Ho	75	12	6.84×10^4	1.00×10^7	0	0	0
20	4	^{165}Ho	75	5	6.94×10^4	1.00×10^7	0	0	0

9 Event Rate Calculations

Event rates were calculated for LEO (ISS) and GEO environments by combining CREME96 orbital integral flux estimations and simplified SEE cross-sections according to methods described in [Heavy Ion Orbital Environment Single-Event Effects Estimations](#). Assume a minimum shielding configuration of 100mils (2.54mm) of aluminum, and *worst-week* solar activity (this is similar to a 99% upper bound for the environment). Using the 95% upper-bounds for SEL, SEB/SEGR, and SET the event rate calculations for SEL, SEB/SEGR, and SET are shown on [Table 9-1](#), [Table 9-2](#), and [Table 9-2](#), respectively. Note that this number is for reference since no SEL, SEB/SEGR, or SET events were observed.

Table 9-1. SEL Event Rate Calculations for Worst-Week LEO and GEO Orbits

Orbit Type	Onset LET _{EFF} (MeV-cm ² /mg)	CREME96 Integral FLUX (/day/cm ²)	σSAT (cm ²)	Event Rate (/day)	Event Rate (FIT)	MTBE (Years)
LEO (ISS)	75	6.26 × 10 ⁻⁵	9.22 × 10 ⁻⁸	5.77 × 10 ⁻¹²	2.41 × 10 ⁻⁴	4.75 × 10 ⁸
GEO		1.77 × 10 ⁻⁴		1.63 × 10 ⁻¹¹	6.79 × 10 ⁻⁴	1.68 × 10 ⁸

Table 9-2. SEB/SEGR Event Rate Calculations for Worst-Week LEO and GEO Orbits

Orbit Type	Onset LET _{EFF} (MeV-cm ² /mg)	CREME96 Integral FLUX (/day/cm ²)	σSAT (cm ²)	Event Rate (/day)	Event Rate (FIT)	MTBE (Years)
LEO (ISS)	75	6.26 × 10 ⁻⁵	4.61 × 10 ⁻⁸	2.89 × 10 ⁻¹²	1.20 × 10 ⁻⁴	9.49 × 10 ⁸
GEO		1.77 × 10 ⁻⁴		8.15 × 10 ⁻¹²	3.40 × 10 ⁻⁴	3.36 × 10 ⁸

Table 9-3. SET Event Rate Calculations for Worst-Week LEO and GEO Orbits

Orbit Type	Onset LET _{EFF} (MeV-cm ² /mg)	CREME96 Integral FLUX (/day/cm ²)	σSAT (cm ²)	Event Rate (/day)	Event Rate (FIT)	MTBE (Years)
LEO (ISS)	75	6.26 × 10 ⁻⁵	4.61 × 10 ⁻⁸	2.89 × 10 ⁻¹²	1.20 × 10 ⁻⁴	9.49 × 10 ⁸
GEO		1.77 × 10 ⁻⁴		8.15 × 10 ⁻¹²	3.40 × 10 ⁻⁴	3.36 × 10 ⁸

10 Summary

The purpose of this study was to characterize the effect of heavy-ion irradiation on the single-event effect (SEE) performance of the TPS7H4011-SP synchronous buck converter. Heavy-ions with $LET_{EFF} = 75\text{MeV}\cdot\text{cm}^2/\text{mg}$ were used for the SEE characterization campaign. Flux of approximately 5×10^4 ions/cm² × s and fluences of approximately 10^7 ions/cm² per run were used for the characterization. The SEE results demonstrated that the TPS7H4011-SP is free of destructive SEL and SEB and SET/SEFI up to $LET_{EFF} = 75\text{MeV}\cdot\text{cm}^2/\text{mg}$ across the full electrical specifications. CREME96-based worst-week event-rate calculations for LEO(ISS) and GEO orbits for the DSEE and SET are presented for reference.

A Total Ionizing Dose from SEE Experiments

The production TPS7H4011-SP is rated to a total ionizing dose (TID) of 100krad(Si). In the course of the SEE testing, the heavy-ion exposures delivered approximately 10krad(Si) per 10^7 ions/cm² run. The cumulative TID exposure was controlled below 100krad (Si) per unit. All six TPS7H4011-SP devices used in the studies described in this report were fully-functional after the heavy-ion SEE testing was completed.

B References

1. M. Shoga and D. Binder, "Theory of Single Event Latchup in Complementary Metal-Oxide Semiconductor Integrated Circuits", *IEEE Trans. Nucl. Sci.*, Vol. 33(6), Dec. 1986, pp. 1714-1717.
2. G. Bruguier and J. M. Palau, "Single particle-induced latchup", *IEEE Trans. Nucl. Sci.*, Vol. 43(2), Mar. 1996, pp. 522-532.
3. G. H. Johnson, J. H. Hohl, R. D. Schrimpf and K. F. Galloway, "Simulating single-event burnout of n-channel power MOSFET's," in IEEE Transactions on Electron Devices, vol. 40, no. 5, pp. 1001-1008, May 1993.
4. J. R. Brews, M. Allenspach, R. D. Schrimpf, K. F. Galloway, J. L. Titus and C. F. Wheatley, "A conceptual model of a single-event gate-rupture in power MOSFETs," in IEEE Transactions on Nuclear Science, vol. 40, no. 6, pp. 1959-1966, Dec. 1993.
5. G. H. Johnson, R. D. Schrimpf, K. F. Galloway, and R. Koga, "Temperature dependence of single event burnout in n-channel power MOSFETs [for space application]," *IEEE Trans. Nucl. Sci.*, 39(6), Dec. 1992, pp.1605-1612.
6. Texas A&M University, [Cyclotron Radiation Effects Facility](#), webpage.
7. Ziegler, James F. [The Stopping and Range of Ions in Matter \(SRIM\) software tools](#), webpage.
8. D. Kececioglu, "Reliability and Life Testing Handbook", Vol. 1, PTR Prentice Hall, New Jersey, 1993, pp. 186-193.
9. Vanderbilt University, [ISDE CRÈME-MC](#), webpage.
10. A. J. Tylka, J. H. Adams, P. R. Boberg, et al., "CREME96: A Revision of the Cosmic Ray Effects on Micro-Electronics Code", *IEEE Trans. on Nucl. Sci.*, Vol. 44(6), Dec. 1997, pp. 2150-2160.
11. A. J. Tylka, W. F. Dietrich, and P. R. Boberg, "Probability distributions of high-energy solar-heavy-ion fluxes from IMP-8: 1973-1996", *IEEE Trans. on Nucl. Sci.*, Vol. 44(6), Dec. 1997, pp. 2140-2149.

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